

# AN6631S

## Direct-Drive Motor Control Circuit

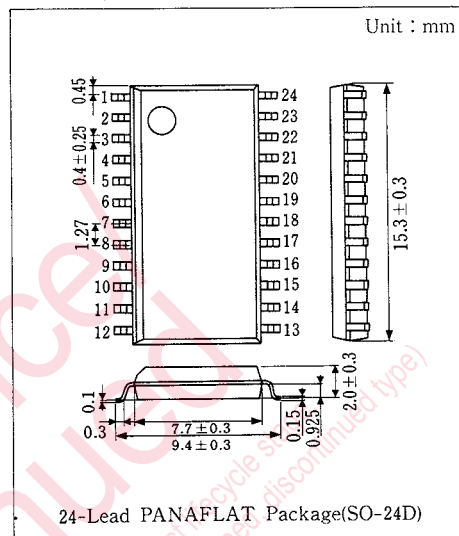
### ■ Outline

The AN6631S is an integrated circuit designed for converting a motor FG (Frequency Generator) signal into F/V (Frequency-Voltage) at a sample hold circuit for comparison with a reference signal and control the rotation of a motor.

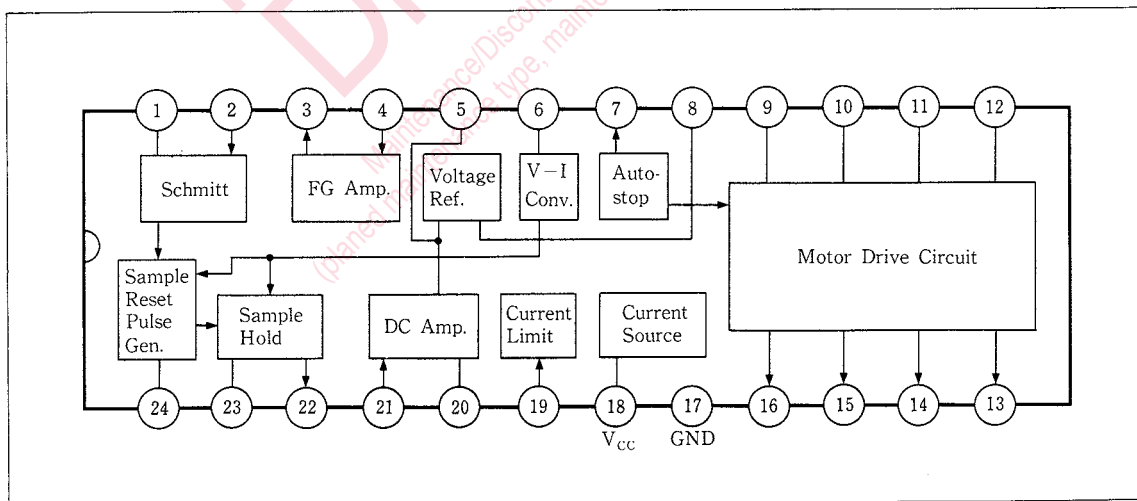
It also has a wide range of operating supply voltage and is suitable for control of a compact DC motor which is used for a tape recorder, etc.

### ■ Features

- 2-phase, all-wave drive.
- Wide range of operating voltage :  $V_{CC}=2\sim 8V$
- Low current consumption :  $I_{CC}=5mA$  typ.



### ■ Block Diagram



## ■ Pin

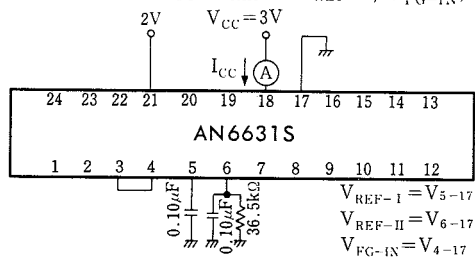
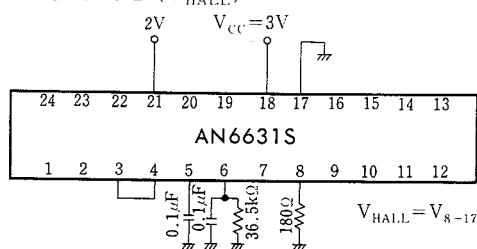
Pin No.	Pin Name	Pin No.	Pin Name
1	Trapezoidal Wave Output	13	Pre-driver Output I
2	Schmitt Circuit Input	14	Pre-driver Output II
3	FG Amp. Output	15	Pre-driver Output III
4	FG Amp. Input	16	Pre-driver Output IV
5	Reference Voltage	17	GND
6	FG Frequency Control	18	V <sub>CC</sub>
7	Stop	19	Current Limit
8	Hall Dev. Bias	20	Invert Amp. Output
9	Hall Dev. A Input I	21	Invert Amp. Input
10	Hall Dev. A Input II	22	Sample & Hold Transf.
11	Hall Dev. B Input I	23	Sample & Hold Output
12	Hall Dev. B Input II	24	Saw Tooth Wave Output

## ■ Absolute Maximum Ratings (Ta=25°C)

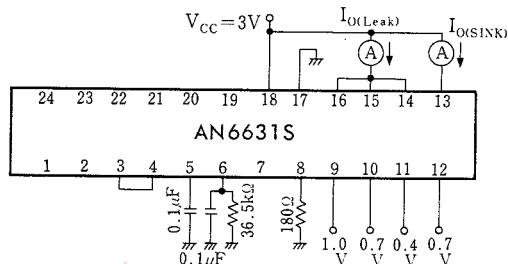
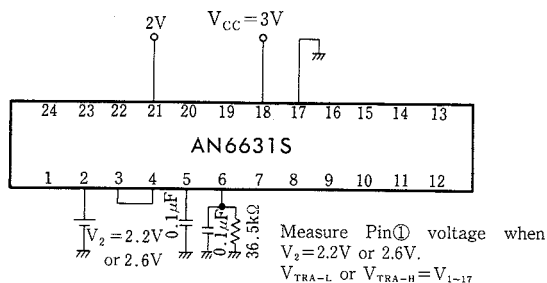
Item	Symbol	Rating	Unit
Supply Voltage	V <sub>CC</sub>	8	V
Supply Current	I <sub>CC</sub>	15	mA
Power Dissipation	P <sub>D</sub>	120	mW
Operating Ambient Temperature	T <sub>opr</sub>	-20 ~ +75	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ +125	°C

## ■ Electrical Characteristics (Ta=25°C)

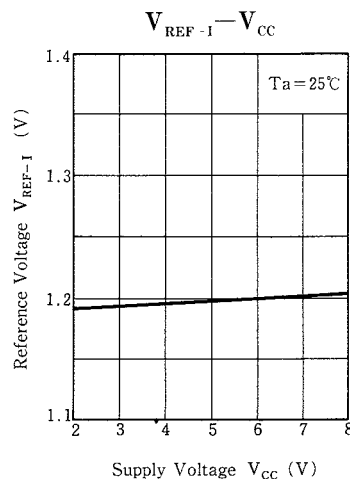
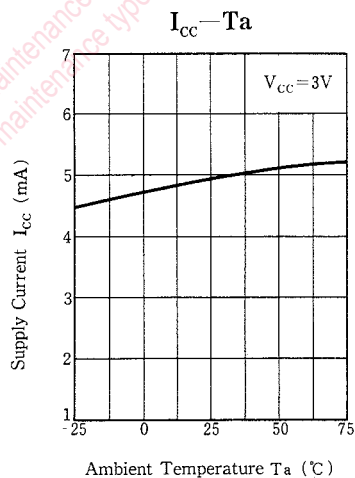
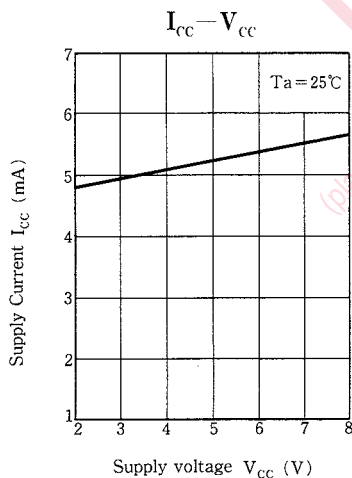
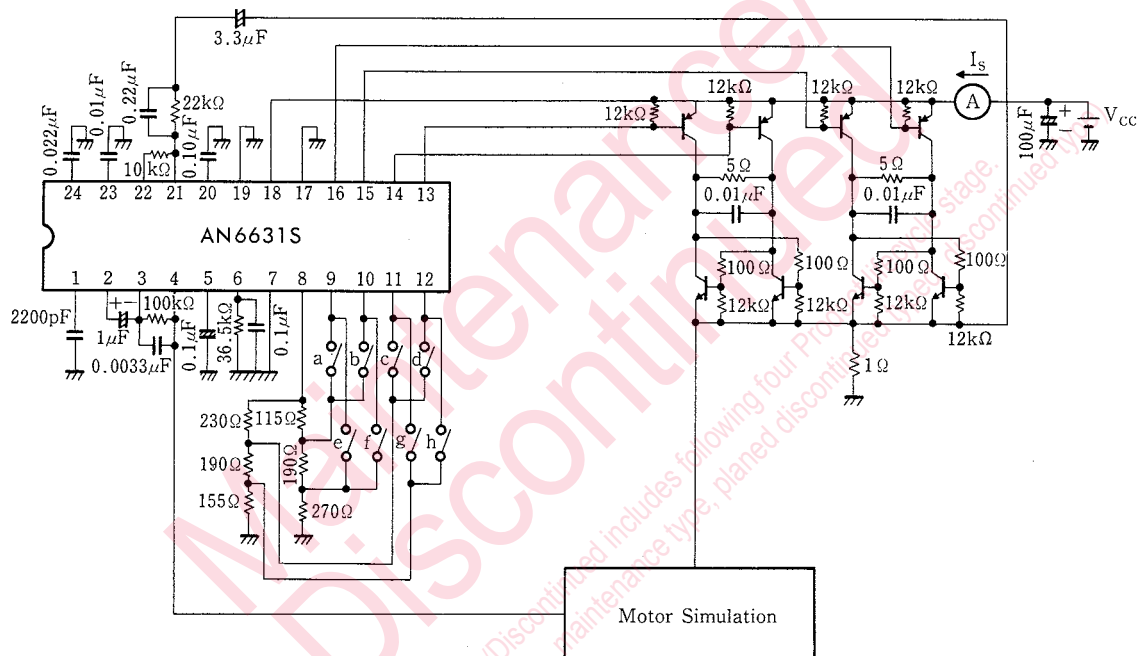
Item	Symbol	Test Circuit	Condition	min.	typ.	max.	Unit
Supply Current	I <sub>CC</sub>	1	V <sub>CC</sub> =3V	3.5	5	7	mA
Reference Voltage(1)	V <sub>REF-I</sub>	1	V <sub>CC</sub> =3V	1.1	1.2	1.3	V
Reference Voltage(2)	V <sub>REF-II</sub>	1	V <sub>CC</sub> =3V	1.1	1.2	1.3	V
Hall Element Drive Voltage	V <sub>HALL</sub>	2	V <sub>CC</sub> =3V	1.1	1.27	1.44	V
FG AMP Input Voltage	V <sub>FG-IX</sub>	1	V <sub>CC</sub> =3V	1.1	1.2	1.3	V
Output Sink Current	I <sub>O(SINK)</sub>	4	V <sub>CC</sub> =3V	7	12		mA
Output Other-Phase Leak Current	I <sub>O(Leak)</sub>	4	V <sub>CC</sub> =3V		20	100	μA
FG AMP Gain	G <sub>V(FG)</sub>	5	V <sub>CC</sub> =3V	48	52		dB
FG Frequency	f <sub>(FG)</sub>	5	V <sub>CC</sub> =3V, I <sub>L</sub> =70mA	1100	1200	1300	Hz
FG Frequency Voltage Characteristics	Δf <sub>V(FG)</sub>	5	V <sub>CC</sub> =2~5V, I <sub>L</sub> =70mA			22	Hz
FG Frequency Load Characteristics	Δf <sub>V(FG)</sub>	5	V <sub>CC</sub> =3V, I <sub>L</sub> =20~120mA			22	Hz
Starting Current	I <sub>S</sub>	5	V <sub>CC</sub> =3V	240	475		mA
Low Level Trapezoidal Wave Output	V <sub>TRA-I</sub>	3	V <sub>CC</sub> =3V, V <sub>2</sub> =2.2V		50	280	mV
High Level Trapezoidal Wave Output	V <sub>TRF-H</sub>	3	V <sub>CC</sub> =3V, V <sub>2</sub> =2.6V	1.38	1.58	1.78	V

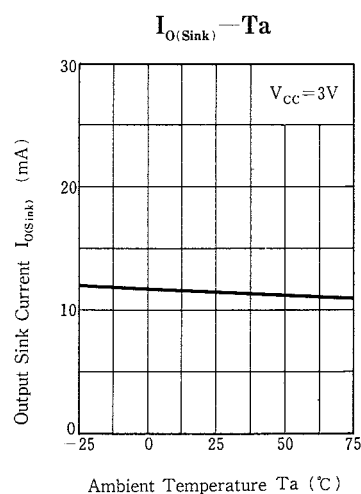
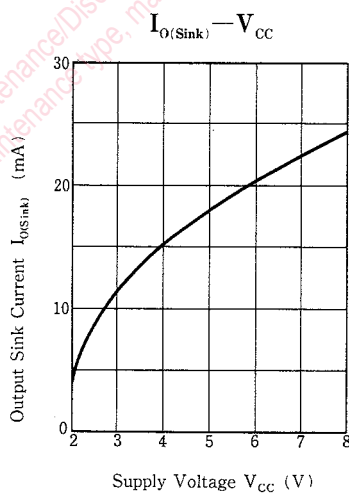
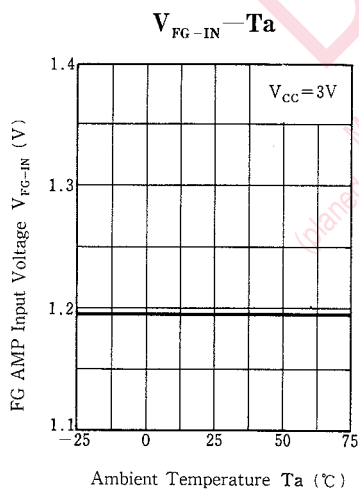
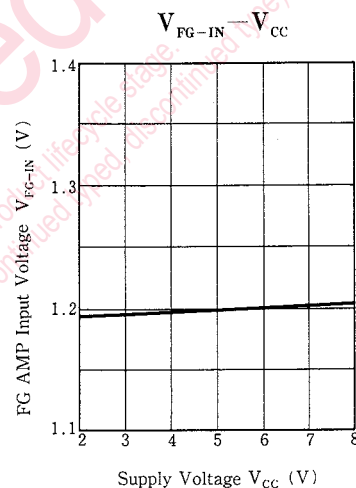
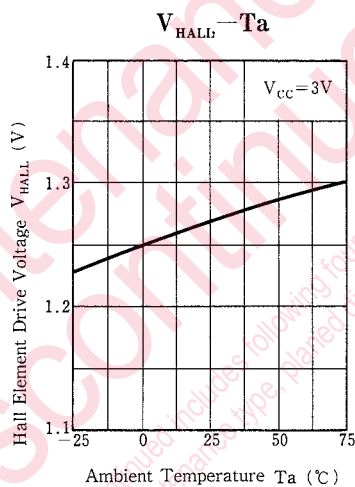
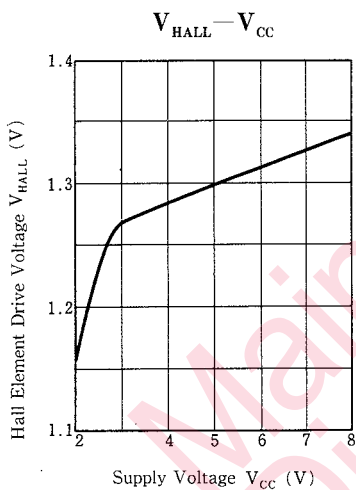
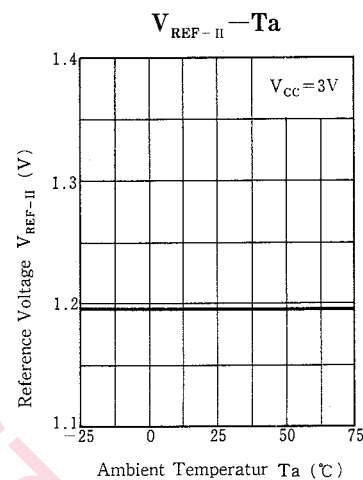
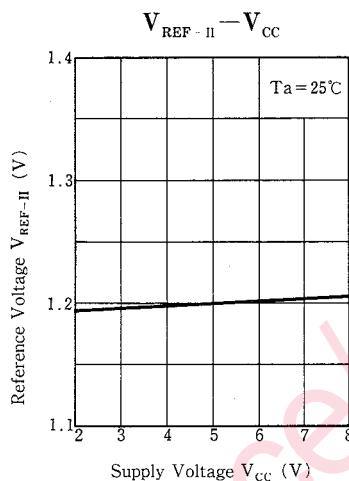
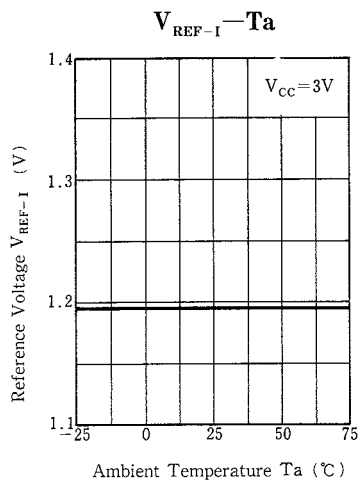
Test Circuit 1 (I<sub>CC</sub>, I<sub>REF-I</sub>, I<sub>REF-II</sub>, V<sub>PG-IX</sub>)Test Circuit 2 (V<sub>HALL</sub>)

### Test Circuit 4 ( $I_{O(SINK)}$ , $I_{O(Leak)}$ )



**Test Circuit 5** ( $G_{V(FG)}$ ,  $f_{(FG)}$ ,  $\Delta f_{(FG)}$ )







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